

SOT2002-1

FM8F, flange mount package, 8 terminals, 5.16 mm pitch, 9.6 mm x 20.395 mm x 3.965 mm body

20 May 2019

Package information

1 Package summary

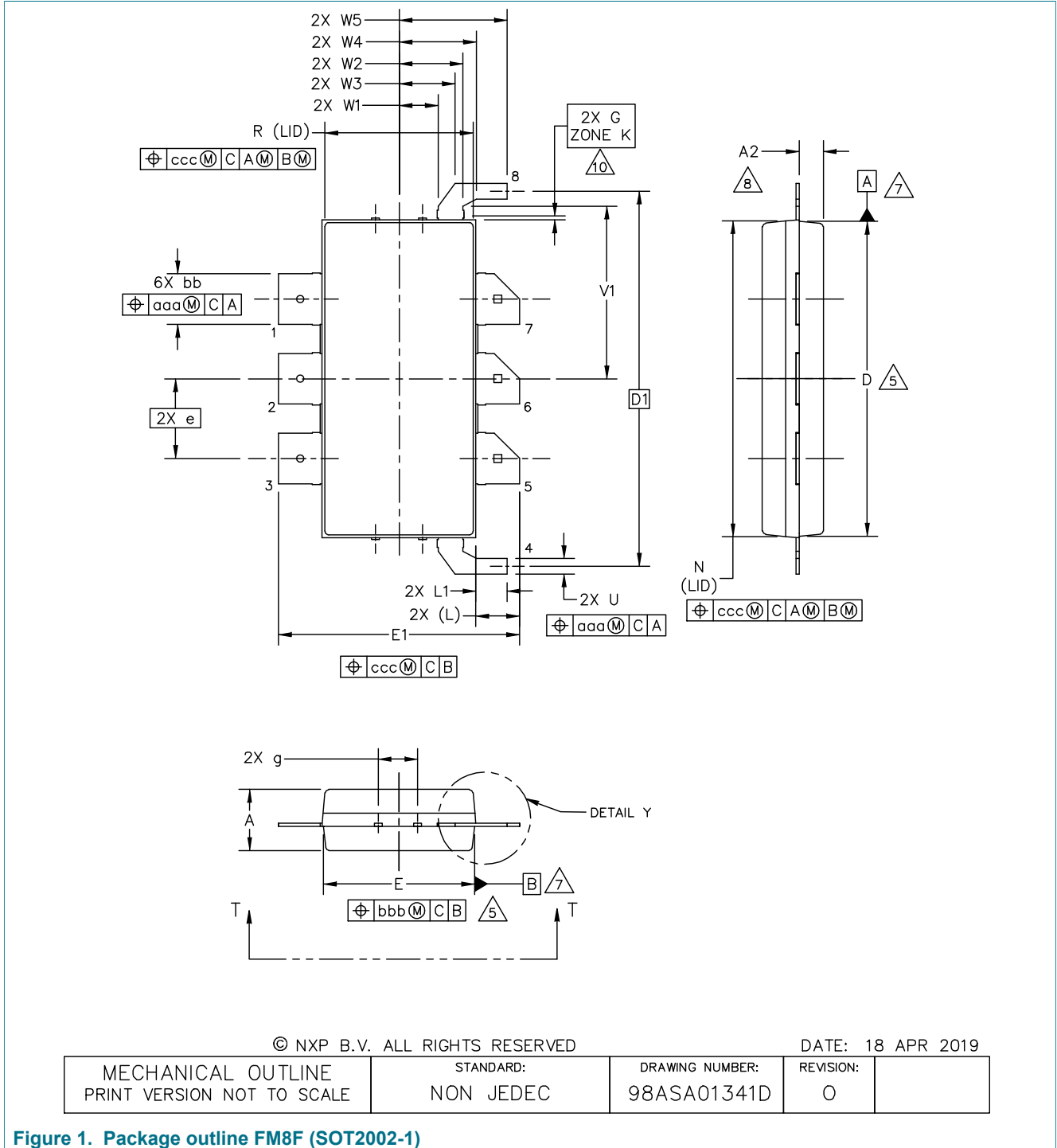
Terminal position code	P (perpendicular)
Package type descriptive code	FM8F
Package style descriptive code	DFM (double-ended flange mount)
Package body material type	P (plastic)
Mounting method type	F (flange mount)
Issue date	18-04-2019
Manufacturer package code	98ASA01341D

Table 1. Package summary

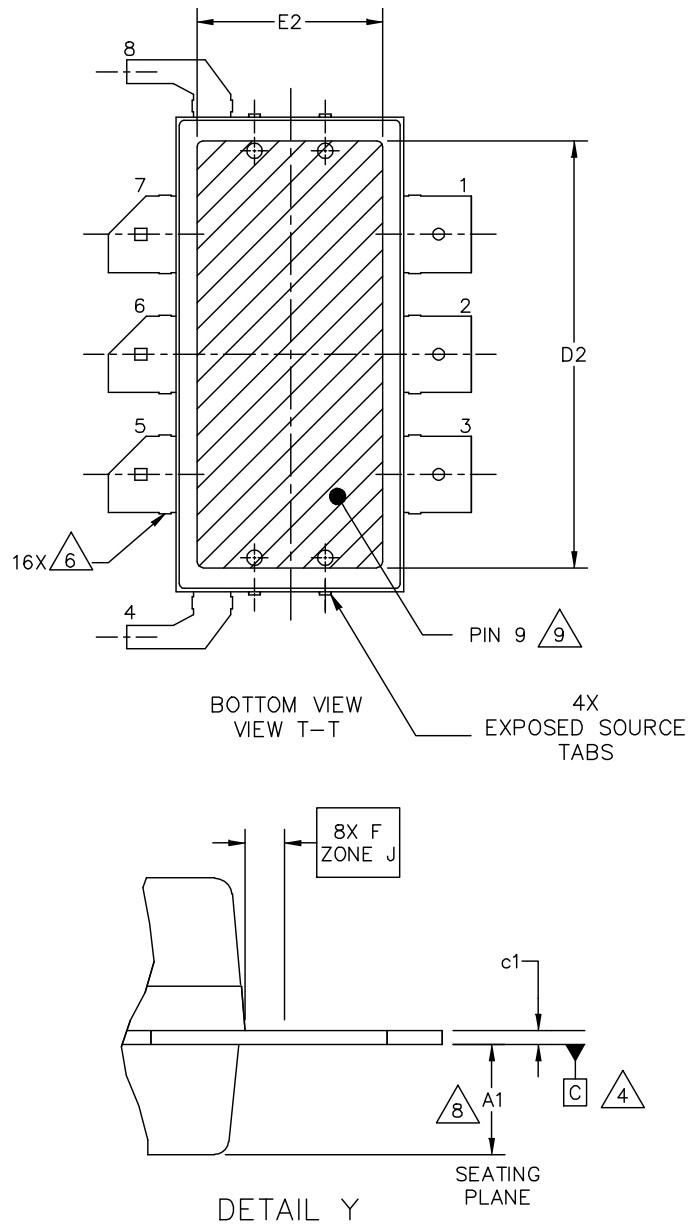
Parameter	Min	Nom	Max	Unit
package length	-	9.6	-	mm
package width	-	20.395	-	mm
package height	-	3.965	-	mm
nominal pitch	-	5.16	-	mm
actual quantity of termination	-	8	-	



2 Package outline



FM8F, flange mount package, 8 terminals, 5.16 mm pitch, 9.6 mm x 20.395 mm x 3.965 mm body



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Figure 2. Package outline detail FM8F (SOT2002-1)

FM8F, flange mount package, 8 terminals, 5.16 mm pitch, 9.6 mm x 20.395 mm x 3.965 mm body

ACM-780-6S2S
SPECIAL

SOT2002-1

NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. UNLESS OTHERWISE SPECIFIED, ALL DIMENSIONS ARE SYMMETRICAL ABOUT CENTERLINES.
4. DATUM C IS LOCATED AT THE BOTTOM OF THE LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
5. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS. ALLOWABLE PROTRUSION IS .006 INCH (0.15 MM) PER SIDE.
6. DIMENSION bb, W1, W2 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION .005 INCH (0.13 MM).
7. DATUM A AND B TO BE DETERMINED AT DATUM PLANE C.
8. DIMENSIONS A1 AND A2 APPLY WITHIN ZONE J ONLY. A1 APPLIES TO PINS 1, 2, 3, 5, 6, AND 7. A2 APPLY TO PINS 4 AND 8.
9. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG. THE DIMENSIONS D2 AND E2 REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF EXPOSED AREA OF HEAT SLUG.
10. ZONE K REPRESENTS NON-SOLDERABLE REGION WHERE MOLD FLASH AND RESIN BLEED ARE PERMITTED ON BOTH SIDES OF THE LEADS.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.146	.166	3.71	4.22	U	.035	.045	0.89	1.14
A1	.059	.065	1.55	1.60	V1	.430	.445	10.92	11.30
A2	.056	.068	1.42	1.73	W1	.095	.105	2.41	2.67
D	.800	.806	20.32	20.47	W2	.158	.168	4.01	4.27
D1	.956 BSC		24.28 BSC		W3	.138	.148	3.51	3.76
D2	.717	---	18.21	---	W4	.192	.202	4.88	5.13
E	.382	.388	9.70	9.86	W5	.435	.445	11.05	11.30
E1	.609	.619	15.47	15.72	bb	.124	.134	3.15	3.40
E2	.309	---	7.85	---	c1	.008	.010	0.20	0.25
F	.030 BSC		0.76 BSC		e	.203 BSC		5.16 BSC	
G	.010 BSC		0.25 BSC		g	.115	.125	2.92	3.18
(L)	.105	.125	2.67	3.18	aaa	.004		0.10	
L1	.074	.094	1.88	2.39	bbb	.006		0.15	
N	.765	.789	19.43	20.04	ccc	.010		0.25	
R	.373	.383	9.47	9.73					



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Figure 3. Package outline note FM8F (SOT2002-1)

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3 Legal information

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